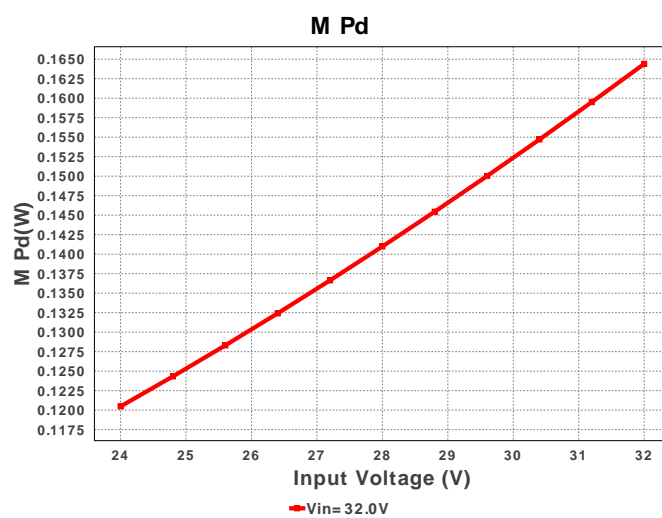
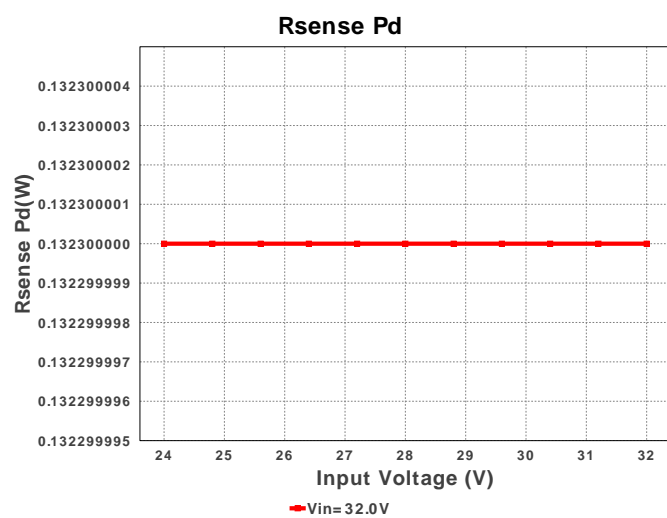
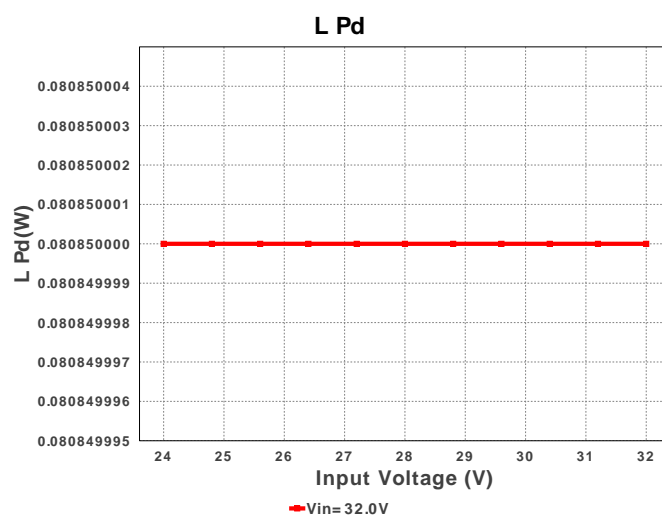
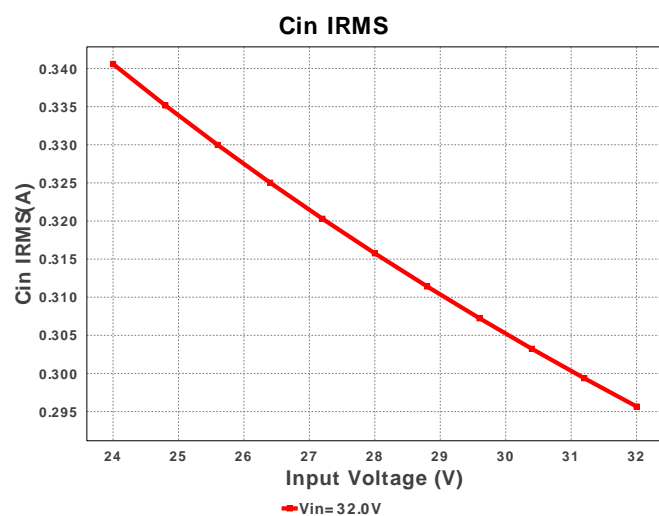
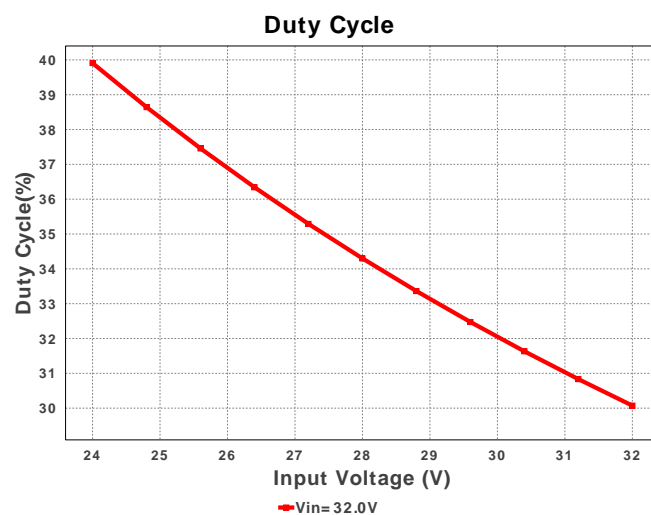
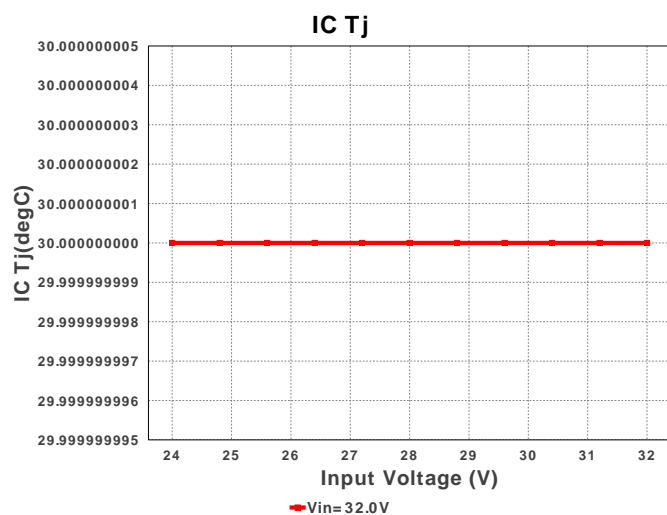
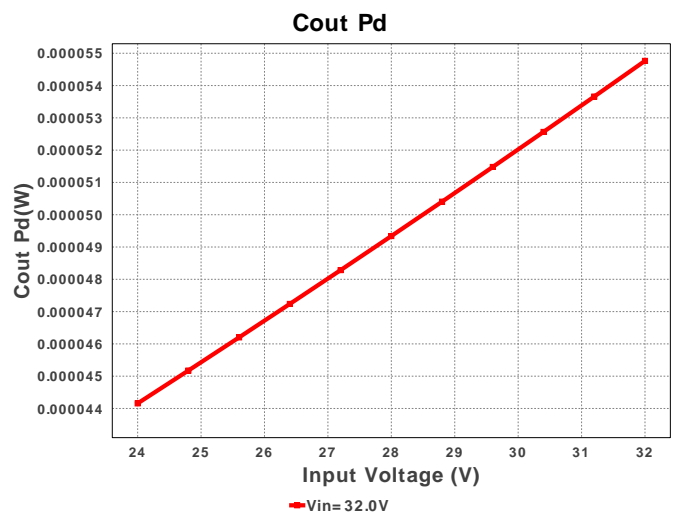
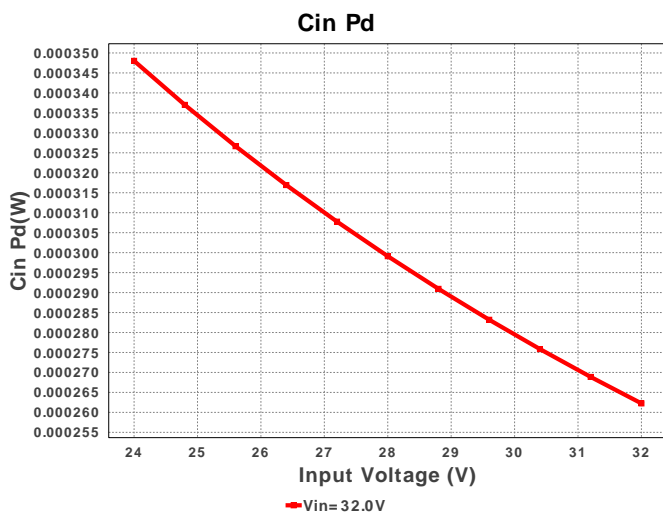
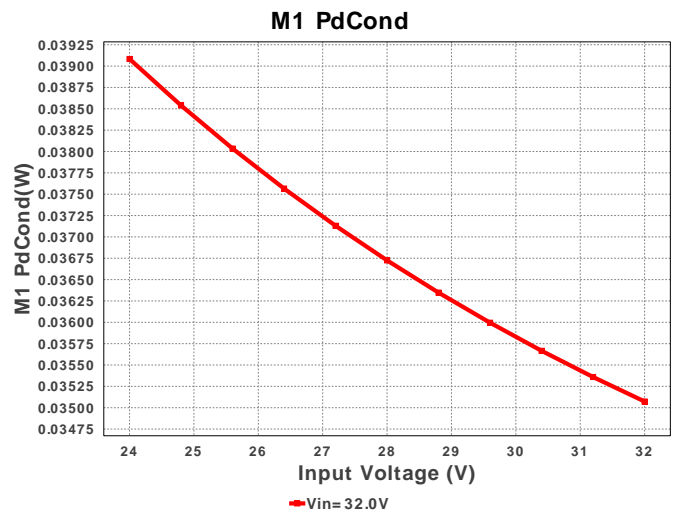
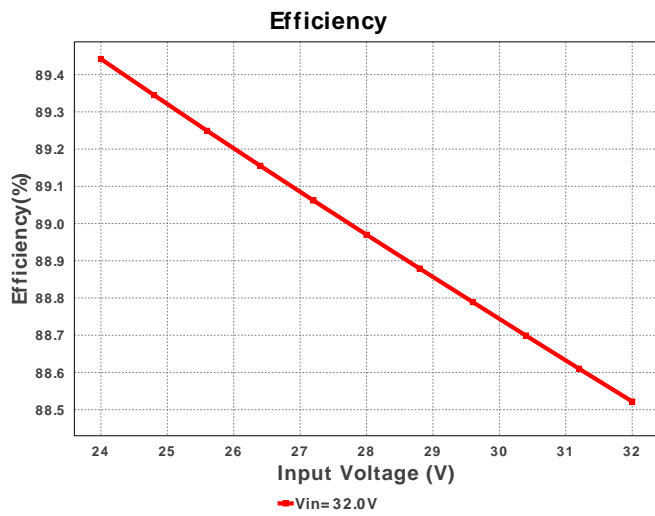
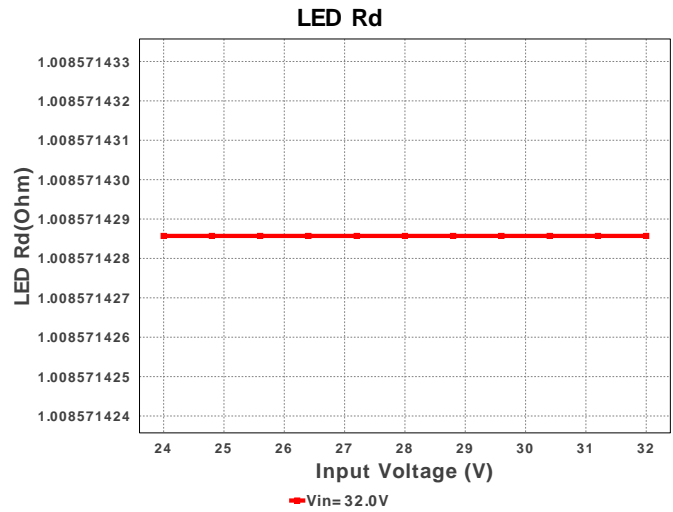
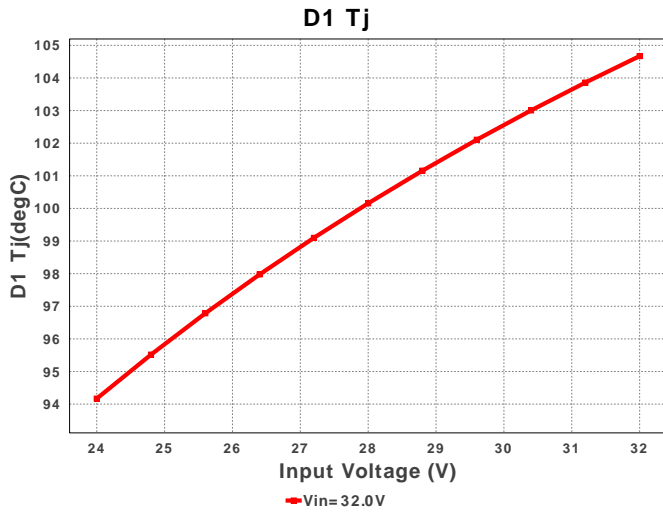
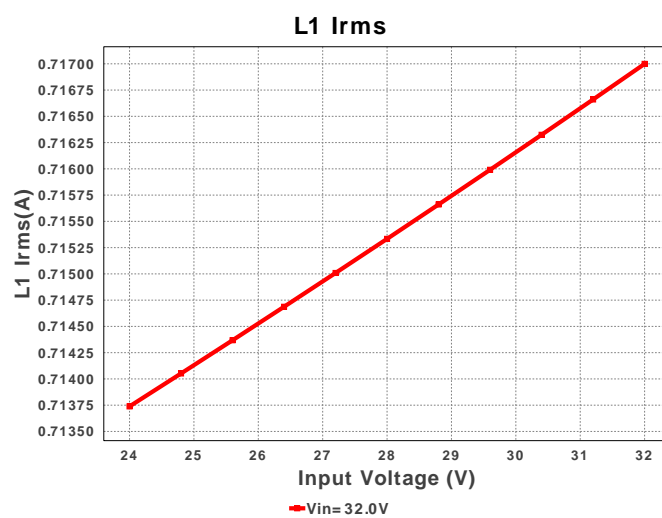
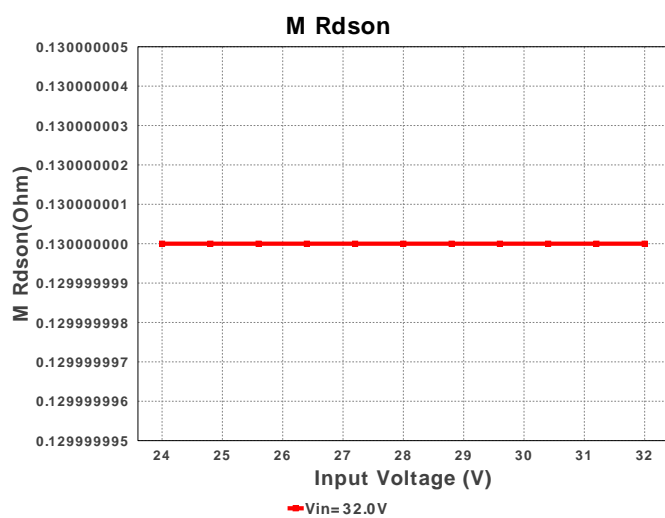
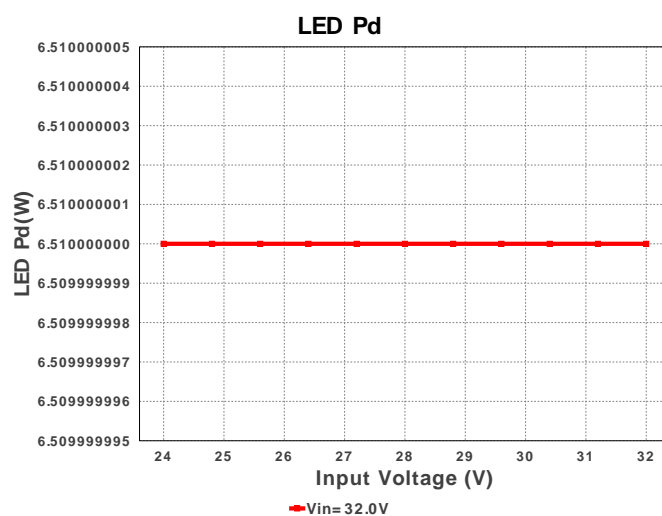
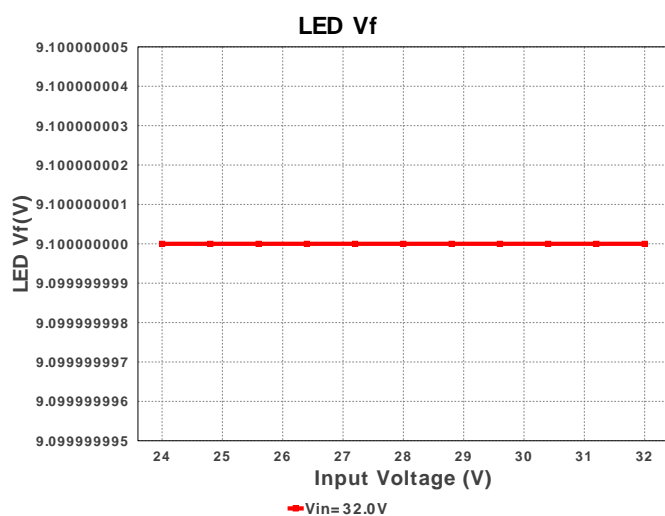
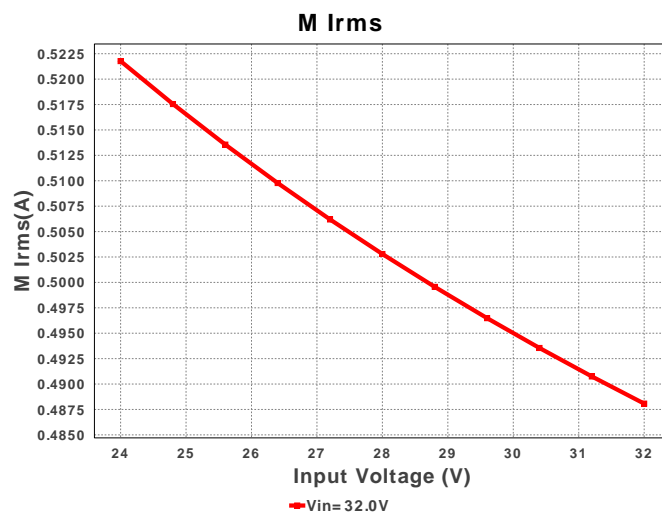
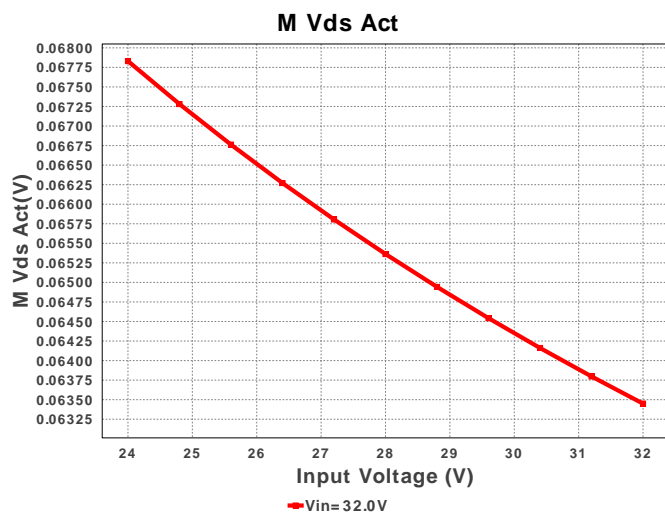


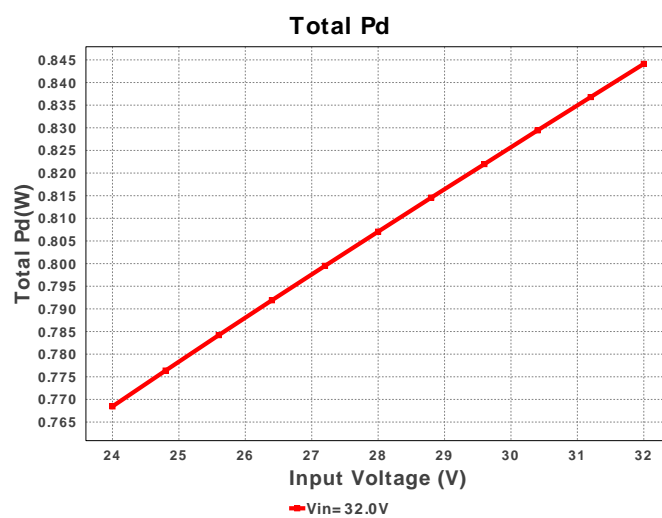
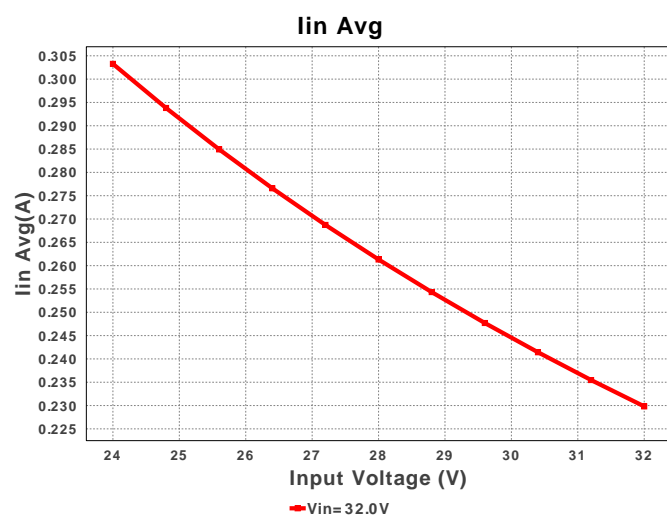
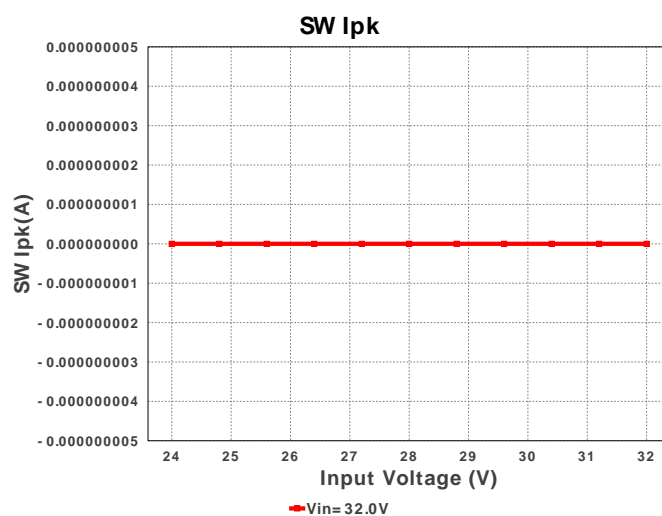
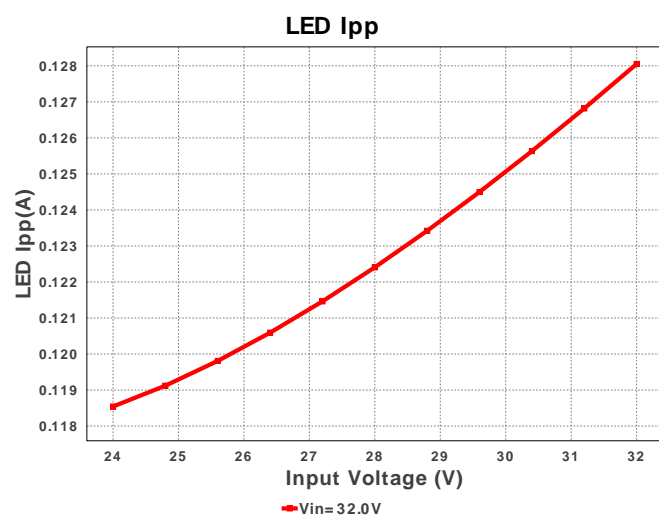
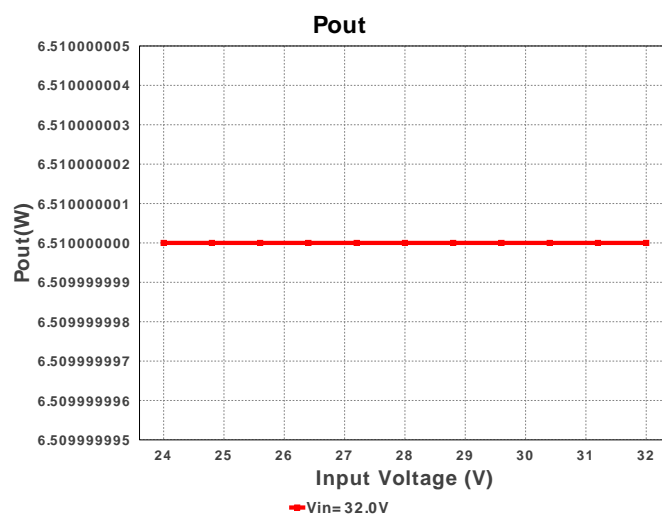
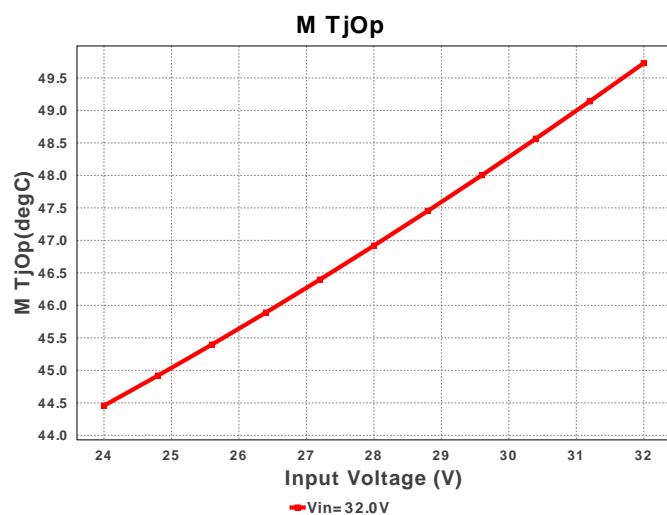


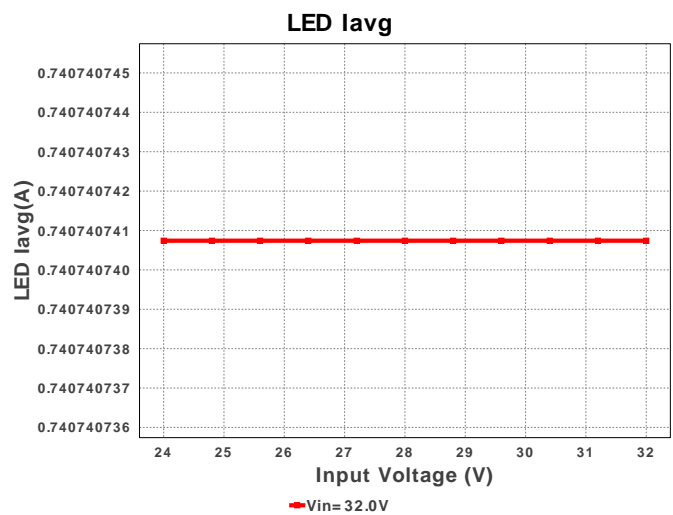
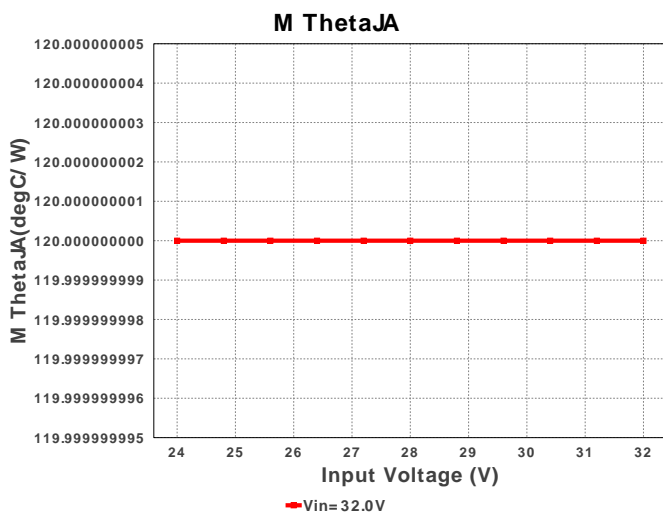
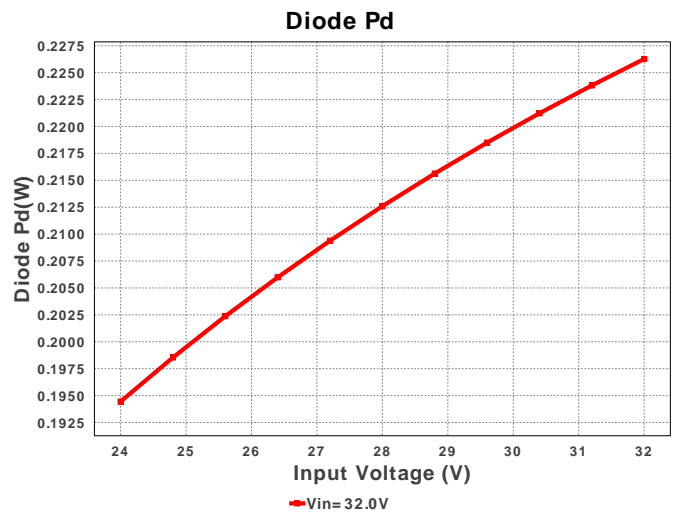
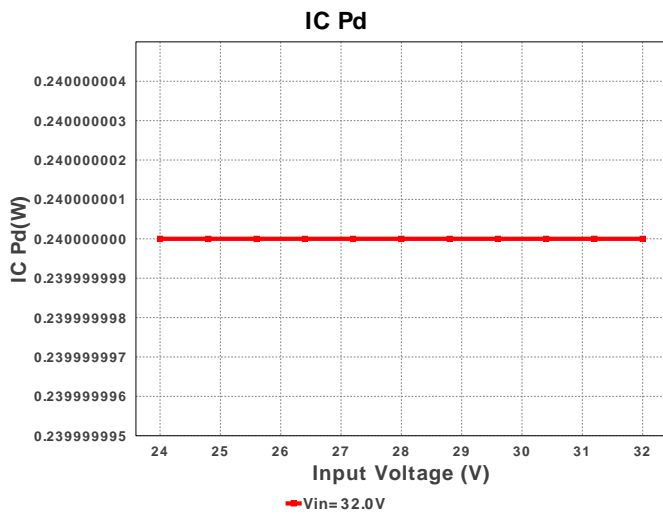
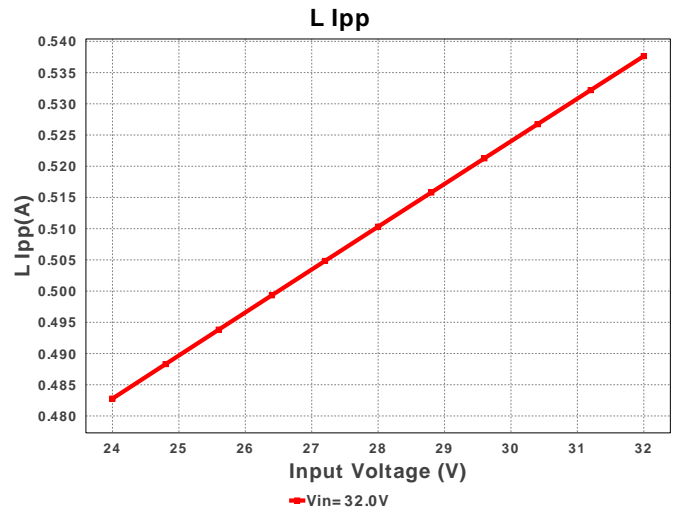
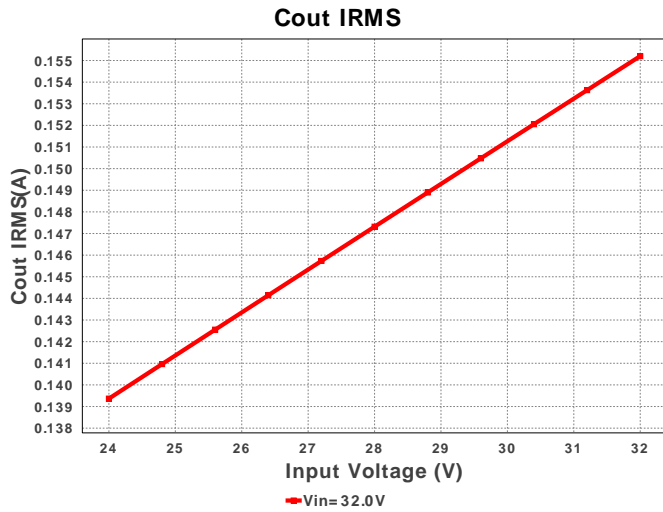
Device = LM3401MM/NOPB
Topology = Buck
Created = 6/9/15 6:04:16 AM
BOM Cost = \$0.00
Footprint = 661.0 mm²
BOM Count = 11
Total Pd = 0.84W

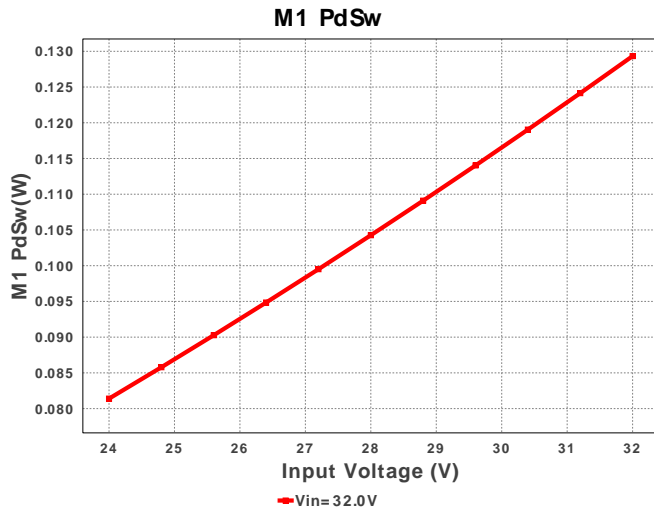












Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	296.575 mA	Current	Input capacitor RMS ripple current
2.	Cout IRMS	156.659 mA	Current	Output capacitor RMS ripple current
3.	Iin Avg	233.96 mA	Current	Average input current
4.	L Ipp	542.68 mA	Current	Peak-to-peak inductor ripple current
5.	L1 Irms	717.316 mA	Current	Inductor ripple current
6.	LED Iavg	740.741 mA	Current	LED Average Current
7.	LED Ipp	129.143 mA	Current	LED Ripple Current
8.	M Irms	493.294 mA	Current	MOSFET RMS ripple current
9.	SW Ipk	0.0 A	Current	Peak switch current
10.	BOM Count	11	General	Total Design BOM count
11.	FootPrint	661.0 mm ²	General	Total Foot Print Area of BOM components
12.	Frequency	706.25 kHz	General	Switching frequency
13.	IC Tolerance	12.0 mV	General	IC Feedback Tolerance
14.	M Rdson	130.0 mOhm	General	Drain-Source On-resistance
15.	M Vds Act	64.128 mV	General	M Vds
16.	Pout	6.65 W	General	Total output power
17.	Total BOM	\$0.0	General	Total BOM Cost
18.	D1 Tj	101.999 degC	Op_Point	D1 junction temperature
19.	Vout OP	9.5 V	Op_Point	Operational Output Voltage
20.	Duty Cycle	30.662 %	Op_point	Duty cycle
21.	Efficiency	88.823 %	Op_point	Steady state efficiency
22.	IC Tj	30.0 degC	Op_point	IC junction temperature
23.	ICThetaJA	151.0 degC/W	Op_point	IC junction-to-ambient thermal resistance
24.	IOUT_OP	700.0 mA	Op_point	Iout operating point
25.	LED Rd	1.009 Ohm	Op_point	LED DynamicResistance
26.	LED Vf	9.3 V	Op_point	Total LED Forward Calculated Voltage
27.	M ThetaJA	120.0 degC/W	Op_point	MOSFET junction-to-ambient thermal resistance
28.	M TjOp	49.821 degC	Op_point	MOSFET junction temperature
29.	VIN_OP	32.0 V	Op_point	Vin operating point
30.	Cin Pd	263.871 μW	Power	Input capacitor power dissipation
31.	Cout Pd	55.796 μW	Power	Output capacitor power dissipation
32.	Diode Pd	218.178 mW	Power	Diode power dissipation
33.	IC Pd	240.0 mW	Power	IC power dissipation
34.	L Pd	80.85 mW	Power	Inductor power dissipation
35.	LED Pd	6.51 W	Power	LED Power Dissipation
36.	M Pd	165.172 mW	Power	MOSFET power dissipation
37.	M1 PdCond	35.843 mW	Power	M1 MOSFET conduction losses
38.	M1 PdSw	129.329 mW	Power	M1 MOSFET switching losses
39.	Rsense Pd	132.3 mW	Power	LED Current Rsns Power Dissipation
40.	Total Pd	836.791 mW	Power	Total Power Dissipation

Design Inputs

#	Name	Value	Description
1.	Iout	700.0 m	Maximum Output Current
2.	Iout1	700.0 m	Output Current #1
3.	VinMax	32.0	Maximum input voltage
4.	VinMin	24.0	Minimum input voltage
5.	Vout	9.3	Output Voltage
6.	Vout1	9.3	Output Voltage #1
7.	application	LED_DRIVER	LED Application
8.	base_pn	LM3401	Base Product Number

#	Name	Value	Description
9.	LED_Architect	N	LED Architect Project
10.	ledparallel	1.0	Number of LED in parallel
11.	ledpartnumber	CL-L103-C6N-C	LED Part number
12.	ledseries	1.0	Number of LED in series
13.	line_fsw	60.0	AC Line Frequency
14.	source	DC	Input Source Type
15.	Ta	30.0	Ambient temperature

Design Assistance

1. **LM3401** Product Folder : <http://www.ti.com/product/LM3401> : contains the data sheet and other resources.

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